

# SN74HC74-Q1 車載認定済み、クリア/プリセット機能搭載、デュアル D タイプ正エッジ・トリガ型フリップ・フロップ

## 1 特長

- 車載アプリケーション用に AEC-Q100 認定済み
  - デバイス温度グレード 1:
    - 40°C ~ +125°C, T<sub>A</sub>
- バッファ付き入力
- 正負入力クランプ・ダイオード
- 広い動作電圧範囲: 2V ~ 6V
- 最大 10 個の LSTTL 負荷ファンアウトに対応
- LSTTL ロジック IC に比べて消費電力を大幅削減

## 2 アプリケーション

- [モメンタリ・スイッチからトグル・スイッチへの変換](#)
- クロック信号の 2 分割または 4 分割

## 3 概要

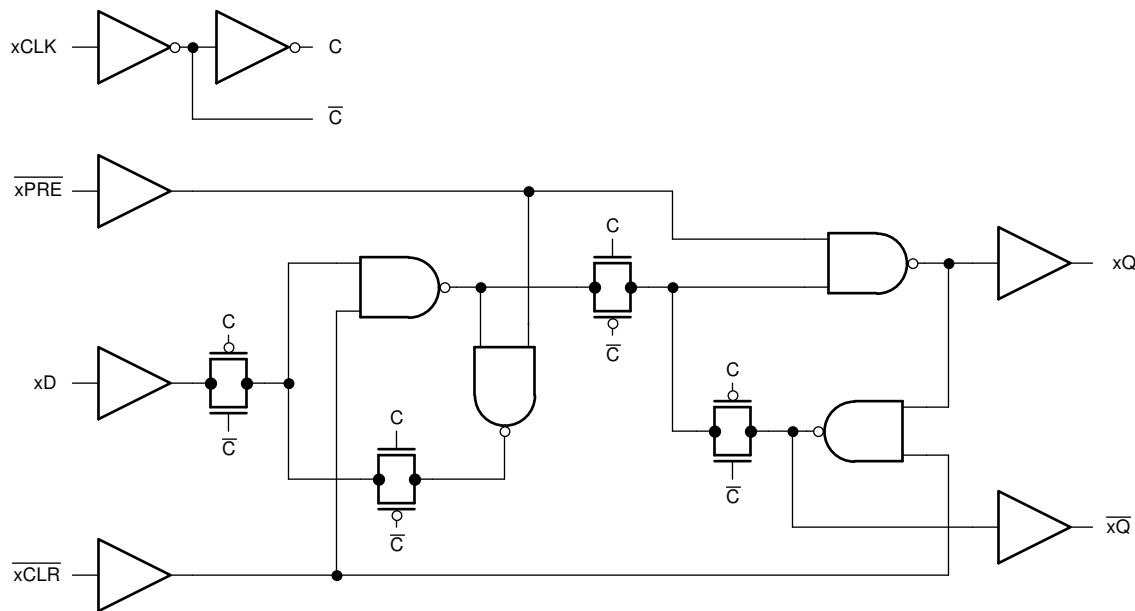
SN74HC74-Q1 には、2 つの独立した D タイプ正エッジ・トリガ型フリップ・フロップが内蔵されており、それぞれに非同期のプリセット・ピンとクリア・ピンが備わっています。

### 製品情報<sup>(1)</sup>

型番	パッケージ	本体サイズ(公称)
SN74HC74QDRQ1	SOIC (14)	8.70mm x 3.90mm
SN74HC74QPWRQ1	TSSOP (14)	5.00mm x 4.40mm

(1) 提供されているすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。

### SN74HC74-Q1 の機能ピン配置



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## 4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

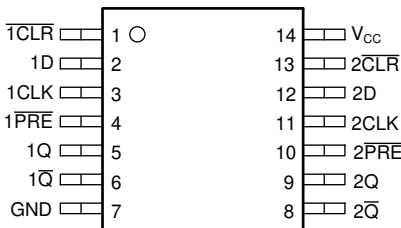
### Revision A (April 2008) から Revision B に変更

**Page**

•	新しいデータシート規格に更新 .....	1
•	Changed $R_{\theta JA}$ for PW package from 113 °C/W to 151.7 °C/W .....	4
•	Changed $R_{\theta JA}$ for D package from 86 °C/W to 133.6 °C/W .....	4

## 5 Pin Configuration and Functions

**D or PW Package  
14-Pin SOIC or TSSOP  
Top View**



**Pin Functions**

PIN		I/O	DESCRIPTION
NAME	NO.		
1 $\overline{\text{CLR}}$	1	Input	Channel 1, Clear Input, Active Low
1D	2	Input	Channel 1, Data Input
1CLK	3	Input	Channel 1, Positive edge triggered clock input
1 $\overline{\text{PRE}}$	4	Input	Channel 1, Preset Input, Active Low
1Q	5	Output	Channel 1, Output
1 $\overline{\text{Q}}$	6	Output	Channel 1, Inverted Output
GND	7	—	Ground
2 $\overline{\text{Q}}$	8	Output	Channel 2, Inverted Output
2Q	9	Output	Channel 2, Output
2 $\overline{\text{PRE}}$	10	Input	Channel 2, Preset Input, Active Low
2CLK	11	Input	Channel 2, Positive edge triggered clock input
2D	12	Input	Channel 2, Data Input
2 $\overline{\text{CLR}}$	13	Input	Channel 2, Clear Input, Active Low
V <sub>CC</sub>	14	—	Positive Supply

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	–0.5	7	V
I <sub>IK</sub>	Input clamp current <sup>(2)</sup>		±20	mA
I <sub>OK</sub>	Output clamp current <sup>(2)</sup>		±20	mA
I <sub>O</sub>	Continuous output current		±25	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>J</sub>	Junction temperature <sup>(3)</sup>		150	°C
T <sub>stg</sub>	Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) Guaranteed by design.

## 6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 <sup>(1)</sup> HBM ESD Classification Level 2	±2000	V
		Charged device model (CDM), per AEC Q100-011 CDM ESD Classification Level C6	±1000	

(1) AEC Q100-002 indicate that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

## 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5		V
		$V_{CC} = 4.5\text{ V}$	3.15		
		$V_{CC} = 6\text{ V}$	4.2		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2\text{ V}$		0.5	V
		$V_{CC} = 4.5\text{ V}$		1.35	
		$V_{CC} = 6\text{ V}$		1.8	
$V_I$	Input voltage	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	V
$\Delta t/\Delta v$	Input transition rise and fall rate	$V_{CC} = 2\text{ V}$		1000	ns
		$V_{CC} = 4.5\text{ V}$		500	
		$V_{CC} = 6\text{ V}$		400	
$T_A$	Operating free-air temperature	–40		125	°C

## 6.4 Thermal Information

THERMAL METRIC	SN74HC74-Q1		UNIT	
	PW (TSSOP)	D (SOIC)		
	14 PINS	14 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	151.7	133.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	79.4	89.0	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	94.7	89.5	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	25.2	45.5	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	94.1	89.1	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

## 6.5 Electrical Characteristics

over operating free-air temperature range; typical values measured at  $T_A = 25^\circ\text{C}$  (unless otherwise noted).

PARAMETER	TEST CONDITIONS	$V_{CC}$	Operating free-air temperature ( $T_A$ )						UNIT	
			25°C			-40°C to 125°C				
			MIN	TYP	MAX	MIN	TYP	MAX		
$V_{OH}$	High-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	$I_{OH} = -20\ \mu\text{A}$	2 V	1.9	1.998		1.9	V	
				4.5 V	4.4	4.499		4.4		
				6 V	5.9	5.999		5.9		
			$I_{OH} = -4\ \text{mA}$	4.5 V	3.98	4.3		3.7		
				6 V	5.48	5.8		5.2		
$V_{OL}$	Low-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	$I_{OL} = 20\ \mu\text{A}$	2 V		0.002	0.1	0.1	V	
				4.5 V		0.001	0.1	0.1		
				6 V		0.001	0.1	0.1		
			$I_{OL} = 4\ \text{mA}$	4.5 V		0.17	0.26	0.4		
				6 V		0.15	0.26	0.4		
$I_I$	Input leakage current	$V_I = V_{CC}$ or 0	6 V		$\pm 0.1$	$\pm 100$		$\pm 1000$	nA	
$I_{CC}$	Supply current	$V_I = V_{CC}$ or 0	$I_O = 0$	6 V			4		80	$\mu\text{A}$
$C_i$	Input capacitance			2 V to 6 V		3	10		10	pF

## 6.6 Timing Characteristics

$C_L = 50\ \text{pF}$ ; over operating free-air temperature range (unless otherwise noted). See [Parameter Measurement Information](#).

PARAMETER		$V_{CC}$	Operating free-air temperature ( $T_A$ )				UNIT
			25°C		-40°C to 125°C		
			MIN	MAX	MIN	MAX	
$f_{\text{clock}}$	Clock frequency	2 V		6		4.2	MHz
		4.5 V		31		21	
		6 V	0	36	0	25	
$t_w$	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	2 V	100		150	ns
			4.5 V	20		30	
			6 V	17		25	
		CLK high or low	2 V	80		120	
			4.5 V	16		24	
			6 V	14		20	
$t_{su}$	Setup time before $\text{CLK}\uparrow$	Data	2 V	100		150	ns
			4.5 V	20		30	
			6 V	17		25	
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	2 V	25		40	
			4.5 V	5		8	
			6 V	4		7	
$t_h$	Hold time, data after $\text{CLK}\uparrow$	2 V	0		0	ns	
		4.5 V	0		0		
		6 V	0		0		

### 6.7 Switching Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM	TO	V <sub>CC</sub>	Operating free-air temperature (T <sub>A</sub> )						UNIT
				25°C			-40°C to 125°C			
				MIN	TYP	MAX	MIN	TYP	MAX	
f <sub>max</sub>	Max switching frequency		2 V	6	10		4.2		MHz	
			4.5 V	31	50		21			
			6 V	36	60		25			
t <sub>pd</sub>	Propagation delay	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	2 V		70	230		345	ns	
			4.5 V		20	46		69		
			6 V		15	39		59		
		CLK	2 V		70	175		250		
			4.5 V		20	35		50		
			6 V		15	30		42		
t <sub>t</sub>	Transition-time	Q or $\overline{\text{Q}}$	2 V		28	75		110	ns	
			4.5 V		8	15		22		
			6 V		6	13		19		

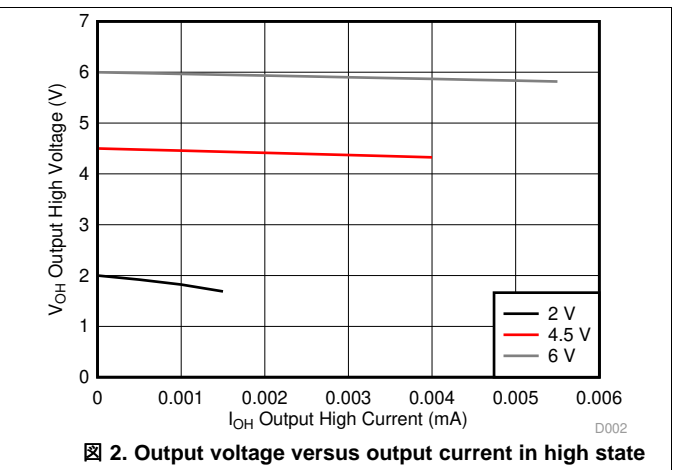
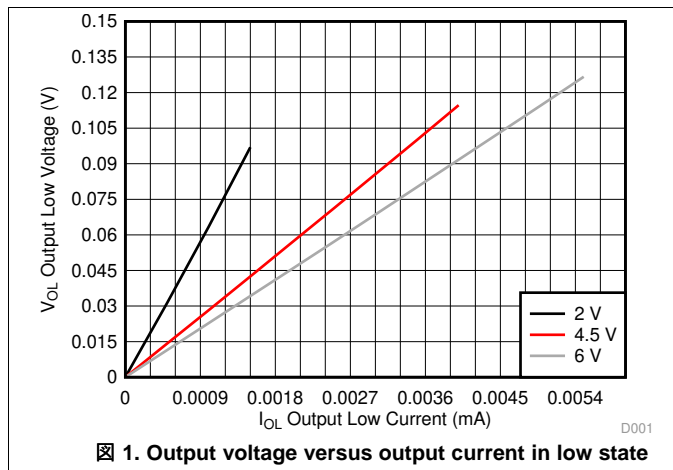
### 6.8 Operating Characteristics

over operating free-air temperature range; typical values measured at T<sub>A</sub> = 25°C (unless otherwise noted).

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate No load		35		pF

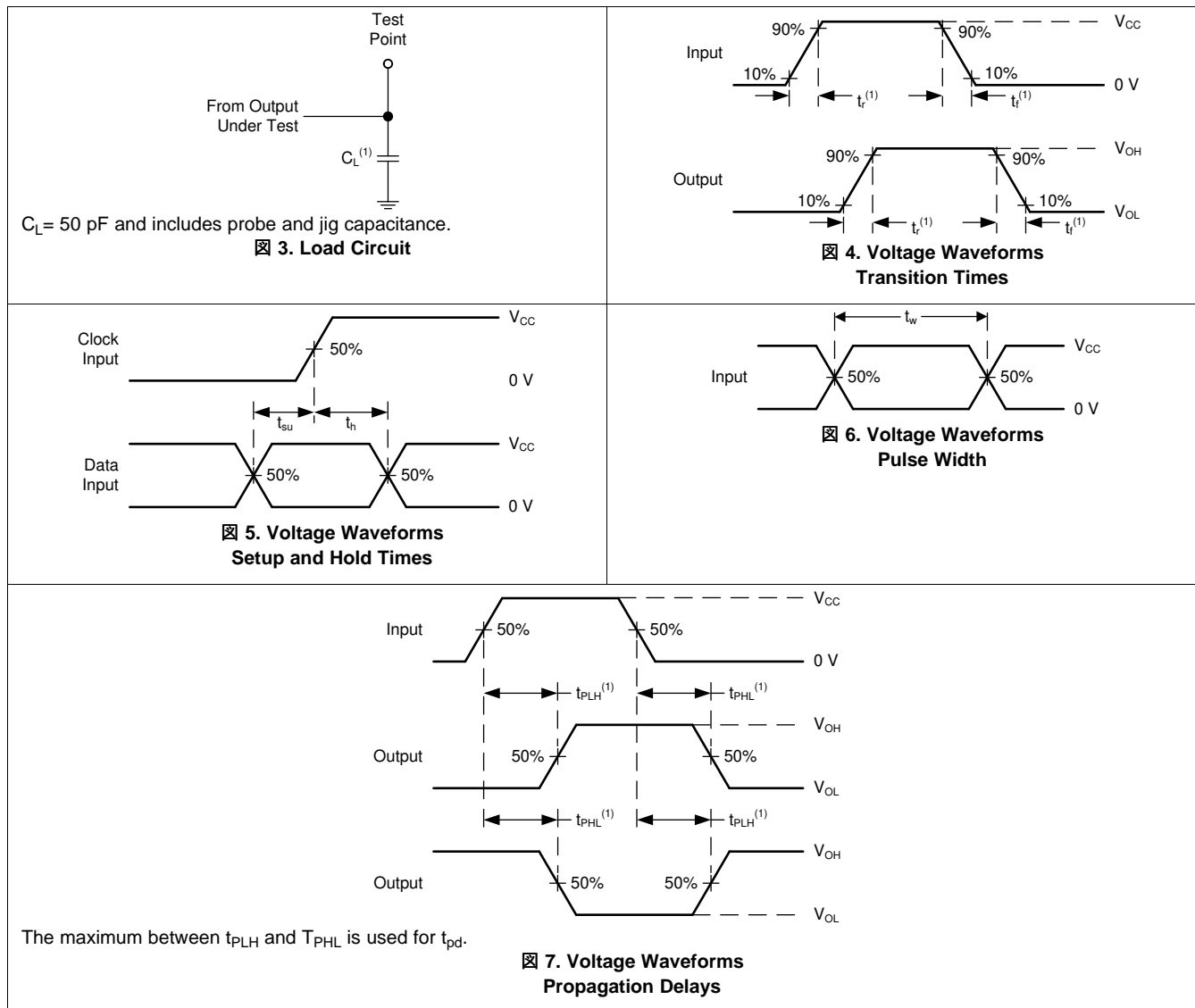
### 6.9 Typical Characteristics

T<sub>A</sub> = 25°C



## 7 Parameter Measurement Information

- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_t < 6 \text{ ns}$ .
- The outputs are measured one at a time, with one input transition per measurement.







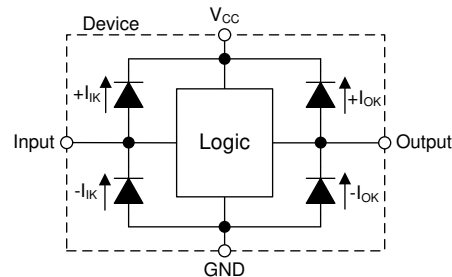
## Feature Description (continued)

### 8.3.3 Clamp Diode Structure

The inputs and outputs to this device have both positive and negative clamping diodes as depicted in 8.

**注意**

Voltages beyond the values specified in the [Absolute Maximum Ratings](#) table can cause damage to the device. The recommended input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



8. Electrical Placement of Clamping Diodes for Each Input and Output

## 8.4 Device Functional Modes

表 1. Function Table

INPUTS				OUTPUT S	
$\overline{\text{PRE}}$	$\overline{\text{CLR}}$	CL K	D	Q	$\overline{\text{Q}}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H <sup>(1)</sup>	H <sup>(1)</sup>
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q <sub>0</sub>	$\overline{\text{Q}}_0$

(1) This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

## 9 Application and Implementation

### 注

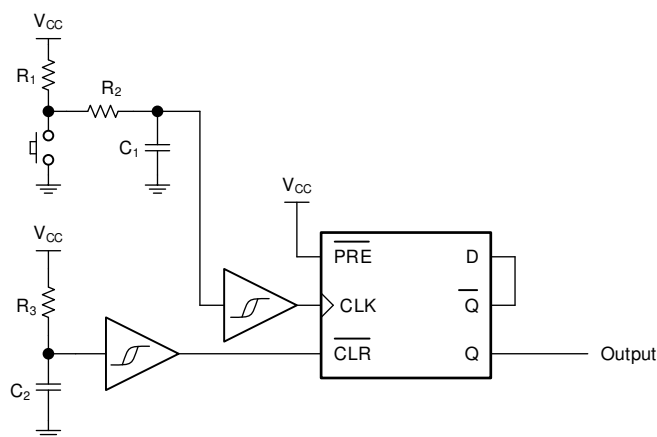
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

Toggle switches are typically large, mechanically complex and relatively expensive. It is desirable to use a momentary switch instead because they are small, mechanically simple and low cost. Some systems require a toggle switch's functionality but are space or cost constrained and must use a momentary switch instead. The SN74HC74-Q1 together with a dual Schmitt-trigger buffer such as SN74LVC2G17 can be used to convert a momentary switch to a toggle switch.

If the data input (D) of the SN74HC74-Q1 is tied to the inverted output ( $\bar{Q}$ ), then each clock pulse will cause the value at the output (Q) to toggle. The momentary switch can be debounced and connected to the buffered clock input (CLK) to toggle the output. These connections are shown in [Figure 9](#).

### 9.2 Typical Application



**Figure 9. Typical application schematic**

#### 9.2.1 Design Requirements

- Most switches require a debounce time constant of at least 10ms ( $2.2 \times R2 \times C1 > 10\text{ms}$ )
- The debounce delay needs to be much smaller than the power on reset circuit's delay to prevent a false trigger during power on ( $R3 \times C3 \gg R2 \times C1$ )
- Conditions for output
  - Q output is LOW at system startup due to the provided reset circuit
  - Each button press will toggle the Q output between LOW and HIGH

##### 9.2.1.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the [Recommended Operating Conditions](#). The supply voltage sets the device's electrical characteristics as described in the [Electrical Characteristics](#).

The supply must be capable of sourcing current equal to the total current to be sourced by all outputs of the SN74HC74-Q1 plus the maximum supply current,  $I_{CC}$ , listed in the [Electrical Characteristics](#). The logic device can only source or sink as much current as it is provided at the supply and ground pins, respectively. Be sure not to exceed the maximum total current through GND or  $V_{CC}$  listed in the [Absolute Maximum Ratings](#).

Total power consumption can be calculated using the information provided in [CMOS Power Consumption and  \$C\_{pd}\$  Calculation](#).

## Typical Application (continued)

Thermal increase can be calculated using the information provided in [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices](#).

### 注意

The maximum junction temperature,  $T_J(\text{max})$  listed in the [Absolute Maximum Ratings](#), is an *additional limitation* to prevent damage to the device. Do not violate any values listed in the [Absolute Maximum Ratings](#). These limits are provided to prevent damage to the device.

### 9.2.1.2 Input Considerations

Unused inputs must be terminated to either  $V_{CC}$  or ground. These can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input is to be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The resistor size is limited by drive current of the controller, leakage current into the SN74HC74-Q1, as specified in the [Electrical Characteristics](#), and the desired input transition rate. A 10-k $\Omega$  resistor value is often used due to these factors.

The SN74HC74-Q1 has standard CMOS inputs, so input signal edge rates cannot be slow. Slow input edge rates can cause oscillations and damaging shoot-through current. The recommended rates are defined in the [Recommended Operating Conditions](#).

Refer to the [Feature Description](#) for additional information regarding the inputs for this device.

### 9.2.1.3 Output Considerations

The positive supply voltage is used to produce the output HIGH voltage. Drawing current from the output will decrease the output voltage as specified by the  $V_{OH}$  specification in the [Electrical Characteristics](#). Similarly, the ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the  $V_{OL}$  specification in the [Electrical Characteristics](#).

Unused outputs can be left floating. Do not connect outputs directly to  $V_{CC}$  or ground.

Refer to [Feature Description](#) for additional information regarding the outputs for this device.

### 9.2.1.4 Timing Considerations

The SN74HC74-Q1 is a clocked device. As such, it requires special timing considerations to ensure normal operation.

Primary timing factors to consider:

- Maximum clock frequency: the maximum operating clock frequency defined in [Timing Characteristics](#) is the maximum frequency at which the device is guaranteed to function. This value refers specifically to the triggering waveform, measuring from one trigger level to the next.
- Pulse duration: ensure that the triggering event duration is larger than the minimum pulse duration, as defined in the [Timing Characteristics](#).
- Setup time: ensure that the data has changed at least one setup time prior to the triggering event, as defined in the [Timing Characteristics](#).
- Hold time: ensure that the data remains in the desired state at least one hold time after the triggering event, as defined in the [Timing Characteristics](#).

## 9.2.2 Detailed Design Procedure

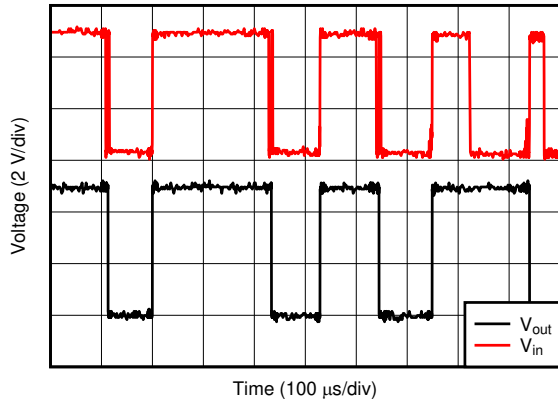
1. Add a decoupling capacitor from  $V_{CC}$  to GND. The capacitor needs to be placed physically close to the device and electrically close to both the  $V_{CC}$  and GND pins. An example layout is shown in the [Layout](#).
2. Ensure the capacitive load at the output is  $\leq 70$  pF. This is not a hard limit, however it will ensure optimal performance. This can be accomplished by providing short, appropriately sized traces from the SN74HC74-Q1 to the receiving device.
3. Ensure the resistive load at the output is larger than  $(V_{CC} / I_O(\text{max})) \Omega$ . This will ensure that the maximum

**Typical Application (continued)**

output current from the *Absolute Maximum Ratings* is not violated. Most CMOS inputs have a resistive load measured in megaohms; much larger than the minimum calculated above.

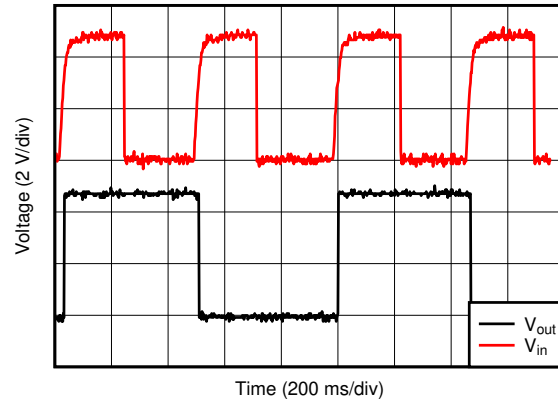
- Thermal issues are rarely a concern for logic gates, however the power consumption and thermal increase can be calculated using the steps provided in the application report, [CMOS Power Consumption and Cpd Calculation](#)

**9.2.3 Application Curves**



D001

**10. Circuit response without RC debounce**  
 $V_{in} := \text{CLK input}, V_{out} := \text{Q output}$



D002

**11. Circuit response with RC debounce**  
 $V_{in} := \text{CLK input}, V_{out} := \text{Q output}$

## 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#). Each  $V_{CC}$  terminal should have a bypass capacitor to prevent power disturbance. A 0.1- $\mu\text{F}$  capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu\text{F}$  and 1- $\mu\text{F}$  capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in [Figure 12](#).

## 11 Layout

### 11.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

### 11.2 Layout Example

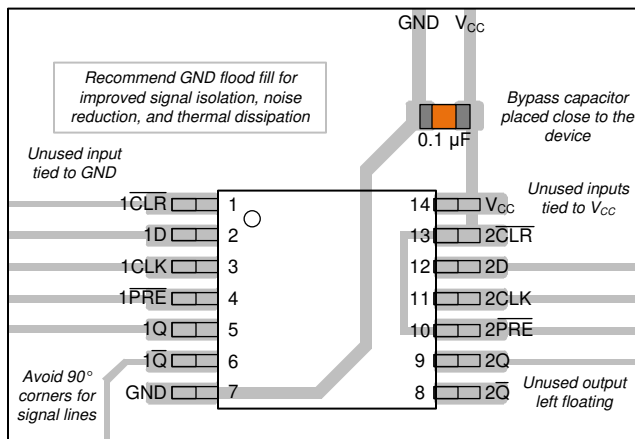


Figure 12. Example layout for the SN74HC74-Q1

## 12 デバイスおよびドキュメントのサポート

### 12.1 ドキュメントのサポート

#### 12.1.1 関連資料

関連資料については、以下を参照してください。

- 『[HCMOS Design Considerations](#)』(英語)
- 『[CMOS Power Consumption and Cpd Calculation](#)』(英語)
- 『[Designing With Logic](#)』(英語)

### 12.2 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびサンプル注文またはご購入へのクイック・アクセスが含まれます。

### 12.3 コミュニティ・リソース

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 12.4 商標

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

### 12.5 静電気放電に関する注意事項



これらのデバイスは、限定的なESD(静電破壊)保護機能を内蔵しています。保存時または取り扱い時は、MOSゲートに対する静電破壊を防止するために、リード線同士をショートさせておくか、デバイスを導電フォームに入れる必要があります。

### 12.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC74QDRG4Q1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC74Q	<a href="#">Samples</a>
SN74HC74QDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC74Q	<a href="#">Samples</a>
SN74HC74QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC74Q	<a href="#">Samples</a>
SN74HC74QPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC74Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74HC74-Q1 :**

- Catalog : [SN74HC74](#)
- Enhanced Product : [SN74HC74-EP](#)
- Military : [SN54HC74](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications



**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC74QDRG4Q1	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC74QDRQ1	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC74QPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC74QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC74QDRG4Q1	SOIC	D	14	2500	356.0	356.0	35.0
SN74HC74QDRQ1	SOIC	D	14	2500	356.0	356.0	35.0
SN74HC74QPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74HC74QPWRQ1	TSSOP	PW	14	2000	356.0	356.0	35.0

D0014A



# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW0014A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

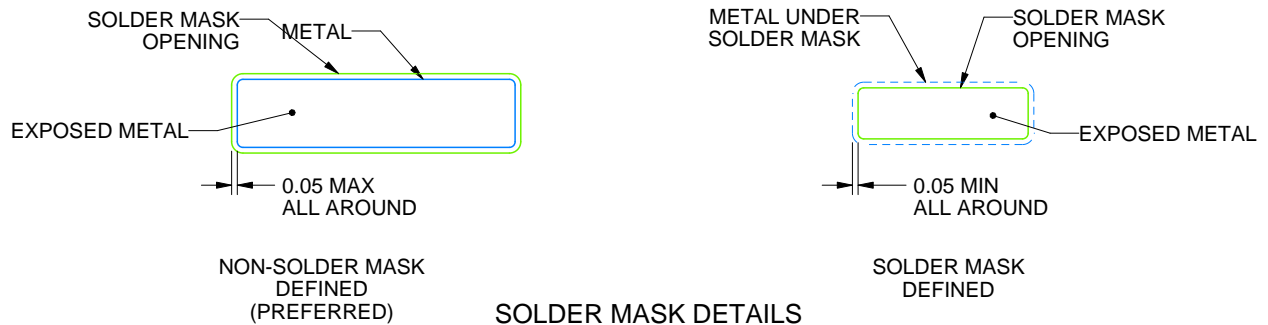
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



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